LEADED

BGA SOLDER PASTE

Sn63/Pb37

Melting point183℃

Product Usage

TIN PASTE

Type number	BST-506
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183℃
G.W.	50g
size	36*36mm

PRODUCT INFORMATION

Low residue
SOLDER PASTE
MODEL: BST-509
ALLOY : Sn63/Pb37
G.W. : 50g
MADE IN CHINA
Solder spot bright
Rapid welding

Welding requirements for a wide range of products

SMT patch

LED patch

BGA welding

Product List

G.W.:50g